









PRODUCT DATASHEET



- ► EMC SMD
- ➤ 3030 0.65t Series
- ► W/R/G/B 4-in-1

N0M62S16





3030 0.65t Series





Release Date: 13 February 2025 Version: A1.1

FEATURES:

Package: TOP View EMC WRGB SMT Package

Forward Current: 100/100/100/100mA*

Forward Voltage (typ.): 3.1/2.3/2.9/3.1V

Luminous Flux (typ.): 38/16/27/7lm@100mA

Colour: Warm White/Red/Green/Blue

CCT/Wavelength: 2700K/622/527/461nm

Viewing Angle: 120°

Materials:

Resin: Silicon

L/T Finish: Ag plated

Operating Temperature: -40~+70°C

Storage Temperature: -40~+70°C

Grouping Parameters:

- Forward Voltage
- Luminous Flux
- CCT/Dominant Wavelength
- Soldering Methods: Reflow
- MSL Level: 3 according to J-STD020
- Packing: 8mm tape with max.5000/reel, ø178mm (7")

APPLICATIONS:

- **Decorative Lighting**
- Portable Lighting
- **Outdoor Lighting**
- **Architectural Lighting**

Commercial Lighting

- Home Appliance
- Led Torch
- Mini Projector

^{*} in order of White/Red/Green/Blue



CHARACTERISTICS:

Absolute Maximum Characteristics (T_a=25°C)

Parameter	Symbol	Ratings	Unit
DC Forward Current	I _F	150	mA
Pulse Forward Current (width≤100μS; duty≤1/10)	I _{FP}	225	mA
Power Dissipation	P _D	525/375/495/525*	mW
Reverse Voltage	VR	5	V
Reverse Current @5V	I _R	10	μΑ
Junction Temperature	Tj	110	°C
Operating Temperature	T _{OPR}	-40~+70	°C
Storage Temperature	T _{STG}	-40~+70	°C
Soldering Temperature	TsoL	230 or 260 for 10S	°C

^{*} in order of White/Red/Green/Blue

Electrical & Optical Characteristics (T_a=25°C)

Darameter	Cumbal		Unit	Test		
Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Forward Voltage	V _F	2.9/1.9/2.7/2.9*	3.1/2.3/2.9/3.1	3.5/2.5/3.3/3.5	V	I _F =100mA
Luminous Flux	Ф۷	34/13/23/5	38/16/27/7	44/25/39/12	lm	I _F =100mA
White Colour Temperature	ССТ		2700		К	I _F =100mA
R/G/B Dominant Wavelength	λ_{D}	617/522/452		626/531/470	nm	I _F =100mA
Viewing Angle	2θ _{1/2}		120		deg	I _F =100mA

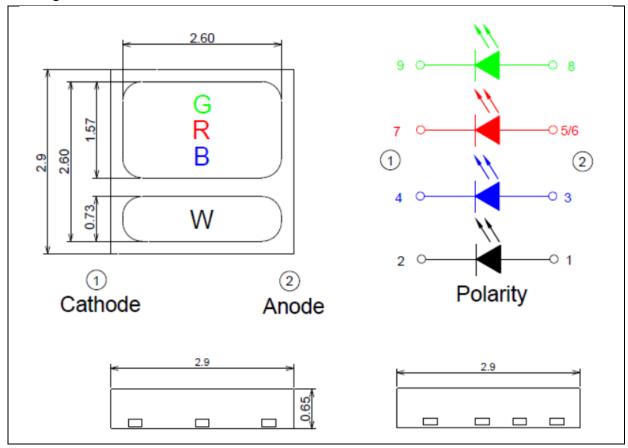
^{1.} Luminous flux (Φ_V) ±10%, Forward Voltage (V_F) ±0.1V

 $^{{\}it 2.} \hspace{0.5cm} \hbox{* in order of White/Red/Green/Blue} \\$



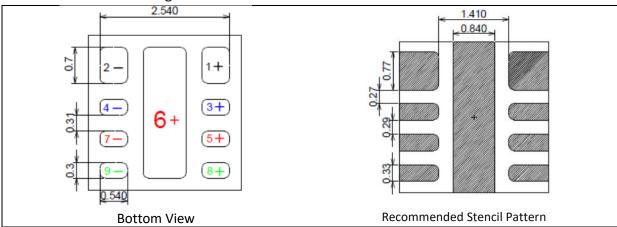
OUTLINE DIMENSION:

Package Dimension:



- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.2mm, unless otherwise noted.

Recommended Soldering Pad Dimension:



- 1. Dimensions are in millimetre (mm).
- 2. Tolerance ±0.1mm with angle tolerance ±0.5°.



BINNING GROUPS:

Forward Voltage Classifications (I_F = 100mA):

Co	ode	Min.	Max.	Unit
White	BB1	2.9	3.5	V
Red	RA1	1.9	2.5	V
Green	GB1	2.9	3.5	V
Blue	BB1	2.9	3.5	V

Luminous Flux Classifications (I_F = 100mA):

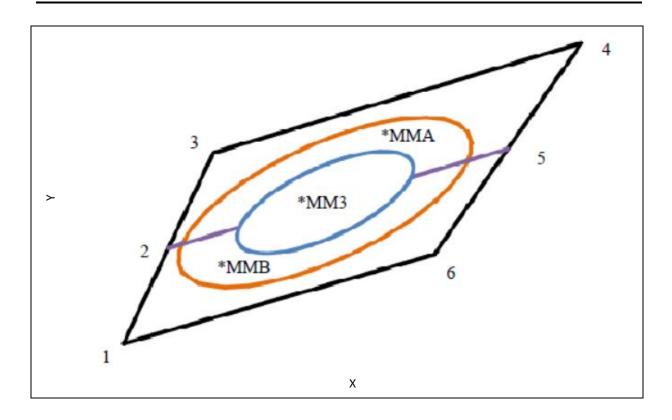
Co	ode	Min.	Max.	Unit
White	WN2	34	44	lm
Dod	RN1	13	19	lue
Red	RN2	19	25	lm
Croon	GN1	23	31	lm
Green	GN2	31	39	lm
Blue	BN2	5	12	lm

Dominant Wavelength Classifications (IF = 100mA):

Code		Min.	Max.	Unit
	RE1	617	620	
Red	RE2	620	623	nm
	RE3	623	626	
	GE2	522	525	
Green	GE3	525	528	nm
	GE4	528	531	
	BE2	452	455	
	BE3	455	458	
Dlug	BE4	458	461	
Blue	BE5	461	464	nm
	BE6	464	467	
	BE7	467	470	



CIE CHROMATICITY DIAGRAM:



Chromaticity Coordinates Classifications (IF = 100mA):

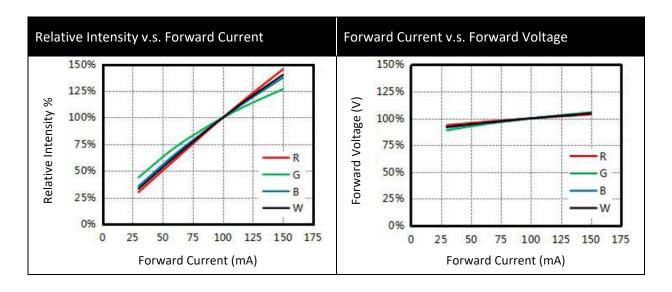
	Cada	Cer	ntre	Rac	lius	Angle
Φ	Code	Х	Υ	а	b	Ф
	8MM-3STEP	0.4582	0.4099	0.008100	0.004200	53.42
	8MM-5STEP	0.4582	0.4099	0.013500	0.007000	53.42

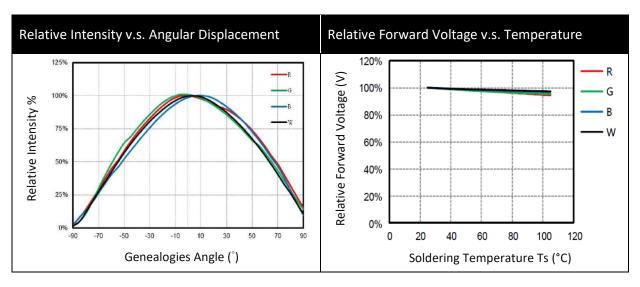
Chromaticity Coordinates Classifications ($I_F = 20mA$):

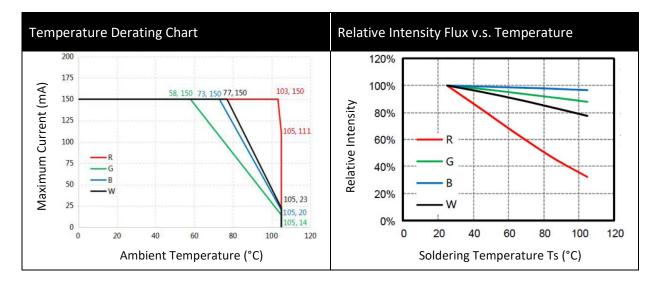
	1	1	2	2	3	3	2	1
	Х	Υ	Х	Y	Х	Υ	Х	Υ
1256	0.4377	0.3891	0.4472	0.4075	0.4707	0.4130	0.4597	0.3942
2345	0.4472	0.4075	0.4566	0.4258	0.4817	0.4317	0.4707	0.4130



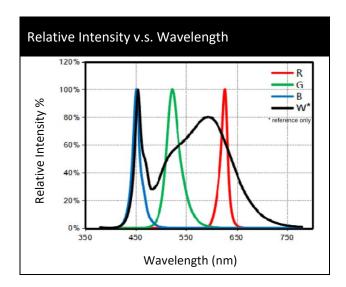
ELECTRO-OPTICAL CHARACTERISTICS:







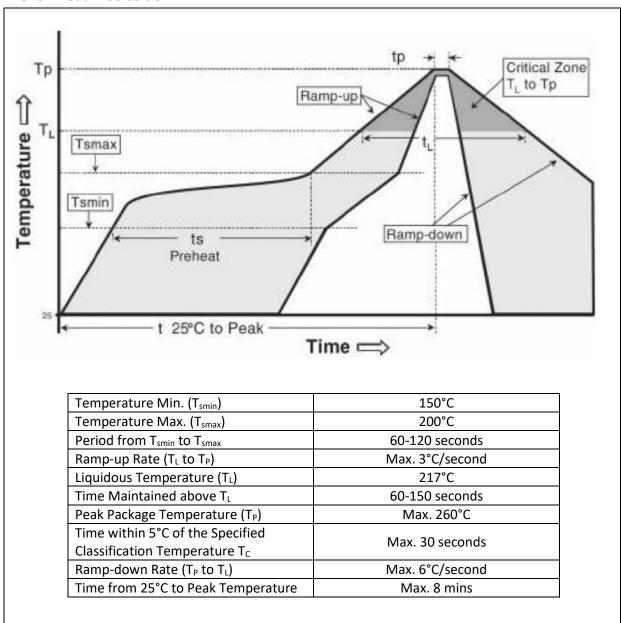






RECOMMENDED SOLDERING PROFILE:

Reflow Lead-free Solder:



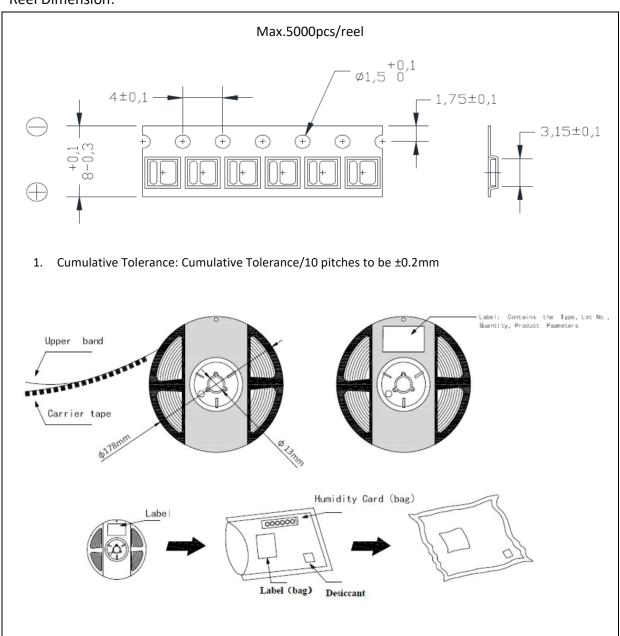
Note:

- 1. Die slug is to be soldered.
- 2. Maximum reflow soldering: 2 times. Between two soldering it should not be longer than 24 hours.
- 3. Before, during, and after soldering, should not apply stress on the components and PCB board.
- 4. Recommended soldering temperature: 240°C. The maximum soldering temperature should be limited to 260°C for max. 10seconds.



PACKING SPECIFICATION:

Reel Dimension:





PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent <10% R.H. and apply baking before use.

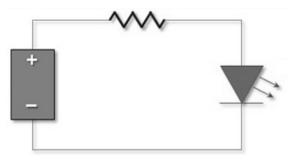
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

• 60±5°C x 24hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.



REVISION RECORD:

Version	Date	Summary of Revision
A1.0	04/09/2022	Datasheet set-up.
A1.1	13/02/2025	Update sorting current to 100mA and add characteristics curves.